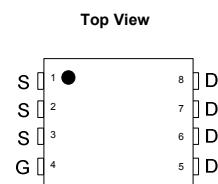
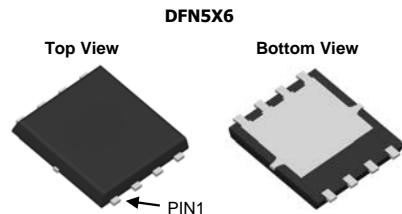


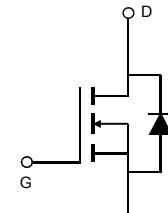
## Features:

- $V_{DS} = 100V, I_D = 80A$
- $R_{DS(ON)} = 6.7\text{ m}\Omega @ V_{GS}=10V$
- $R_{DS(ON)} = 8.4\text{ m}\Omega @ V_{GS}=4.5V$
- N-channel, optimized for high-speed smooth switching
- Excellent Gate Charge  $\times R_{DS(ON)}$  (FOM)
- Very low on-resistance
- RoHS compliant
- Halogen-free



## Applications:

- DC-DC Converter
- Power Management
- Motor Drivers
- Load Switching



## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	80	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	$I_D (100^\circ\text{C})$	63.5	A
Pulsed Drain Current	$I_{DM}$	240	A
Maximum Power Dissipation	$P_D$	52	W
Derating factor		1.50	W/ $^\circ\text{C}$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ\text{C}$



**Electrical Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	100		-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=80\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1.2	1.5	2.2	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=20\text{A}$	-	6.7	9.0	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=10\text{A}$	-	8.4	12.5	
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=80\text{V}, \text{I}_D=20\text{A}$	26	-	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=50\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$		1987		PF
Output Capacitance	$\text{C}_{\text{oss}}$			629		PF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$			12		PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=50\text{V}, \text{I}_D=20\text{A}, \text{R}_{\text{L}}=1\Omega$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_{\text{G}}=3\Omega$	-	15	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	28	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	46	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	42	-	nS
Total Gate Charge	$\text{Q}_{\text{g}}$	$\text{V}_{\text{DS}}=50\text{V}, \text{I}_D=20\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	39		nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	6.6		nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	8.6		nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=20\text{A}$	-	0.7	1.2	V
Diode Forward Current (Note 2)	$\text{I}_{\text{S}}$		-	-	62	A
Reverse Recovery Time	$t_{\text{rr}}$	$\text{T}_{\text{J}} = 25^\circ\text{C}, \text{IF} = 20\text{A}$ $\text{di/dt} = 100\text{A}/\mu\text{s}$ (Note 3)	-	177	-	nS
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	1290	-	nC
Forward Turn-On Time	$t_{\text{ton}}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

## Electrical Characteristics Diagrams

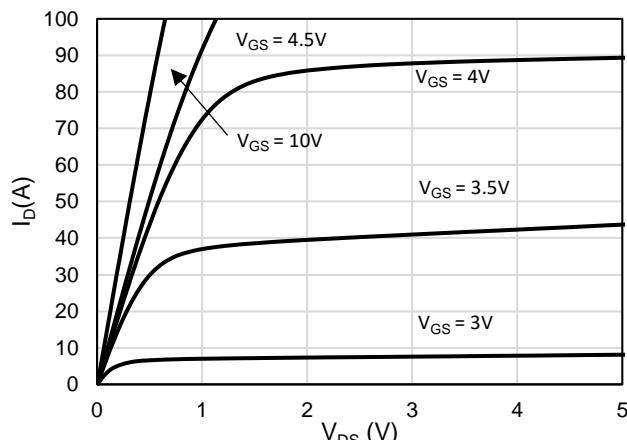


Figure 1: On-Region Characteristics

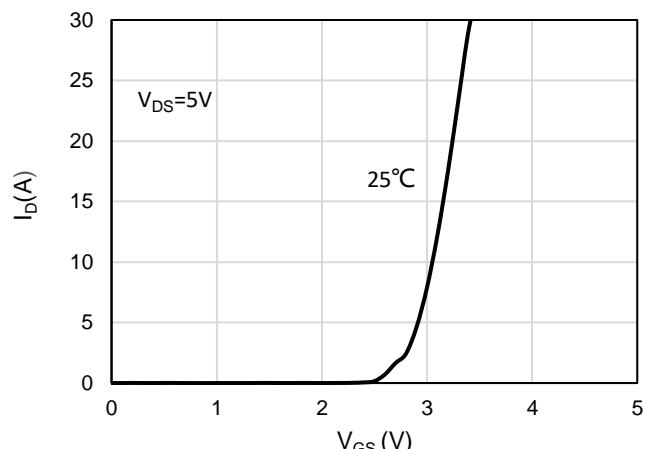


Figure 2: Transfer Characteristics

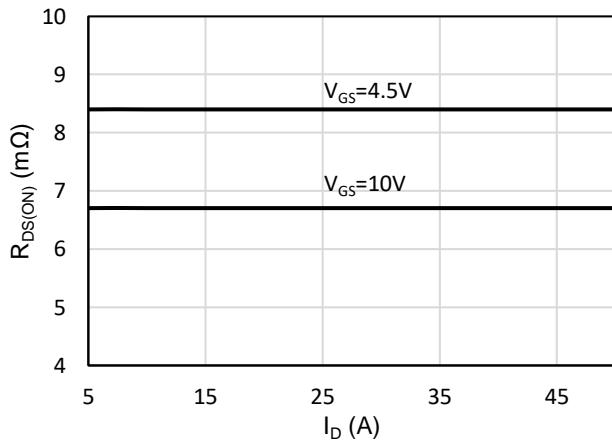


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

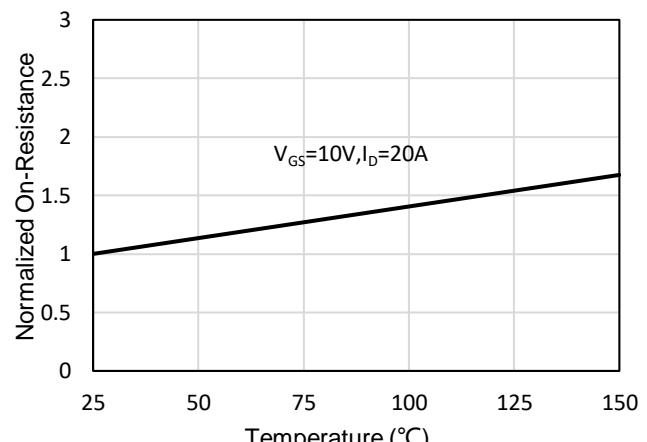


Figure 4: On-Resistance vs. Junction Temperature

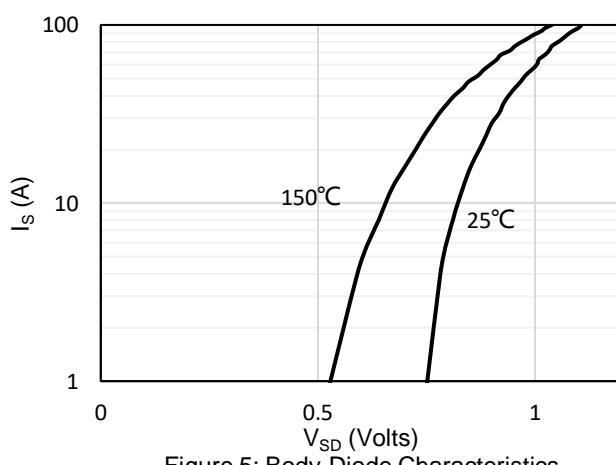


Figure 5: Body-Diode Characteristics

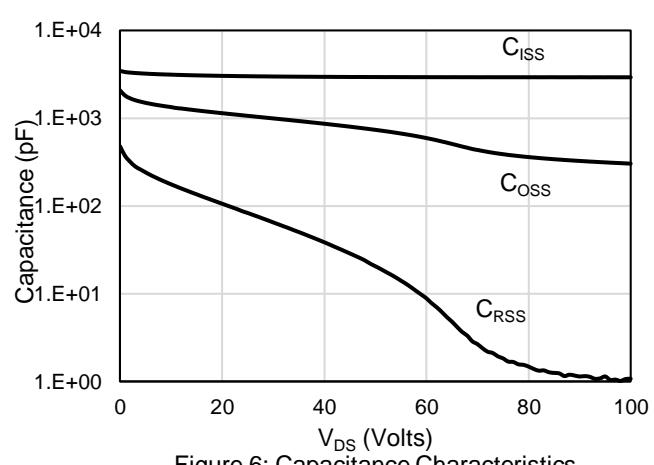


Figure 6: Capacitance Characteristics

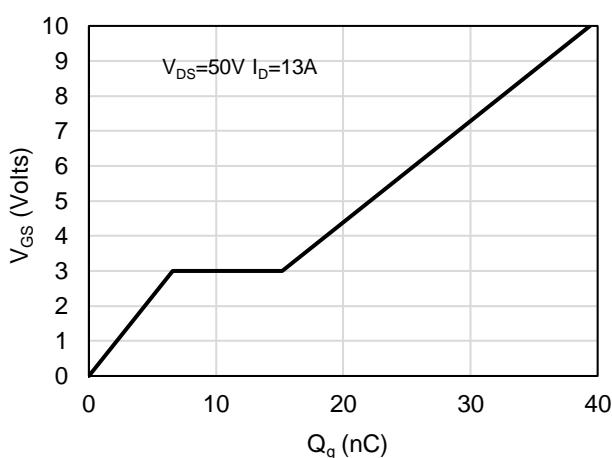


Figure 7: Gate-Charge Characteristics

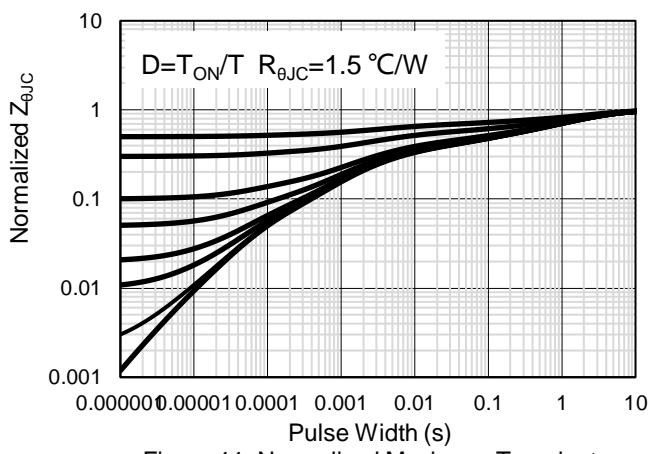
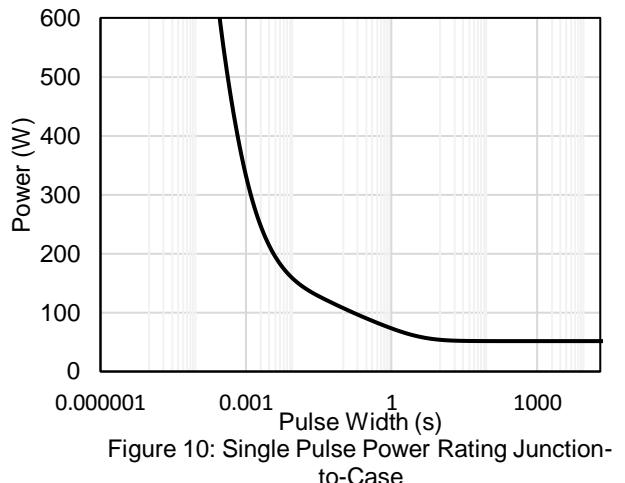
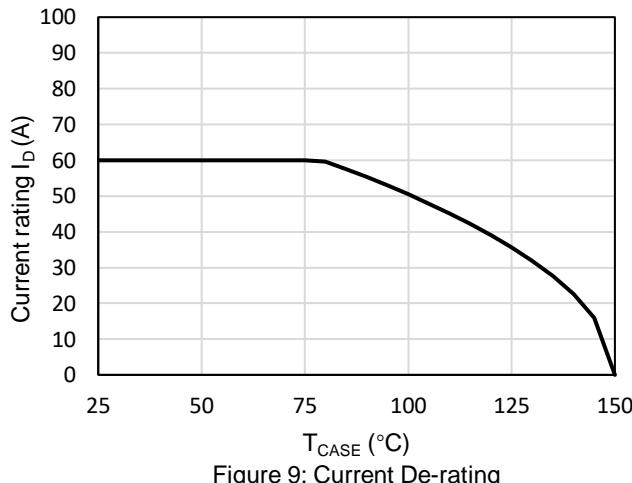
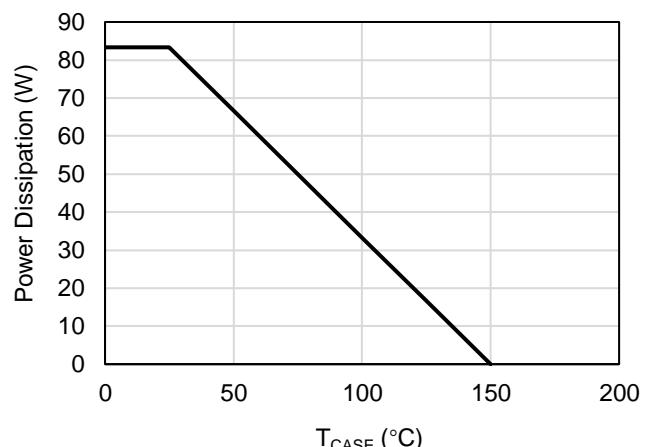


Figure 11: Normalized Maximum Transient Thermal Impedance

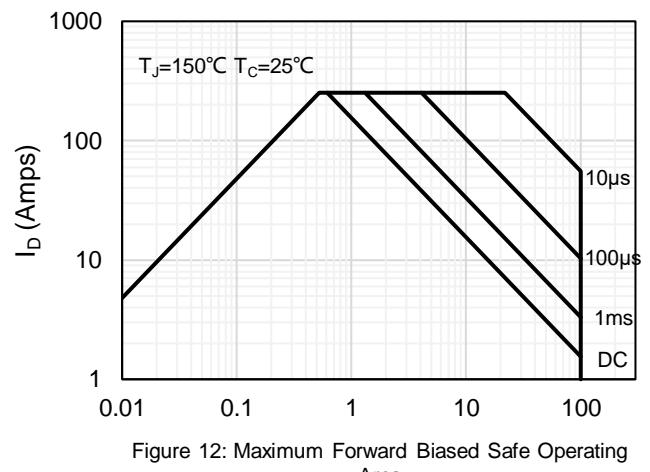
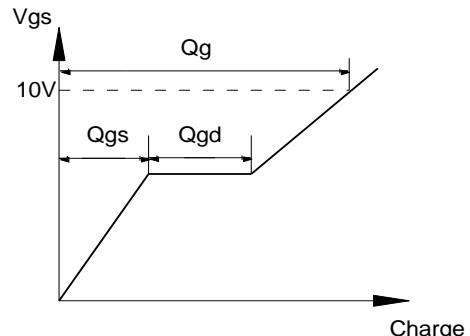
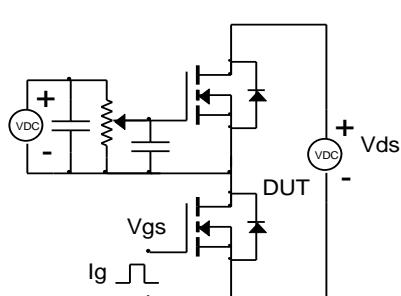


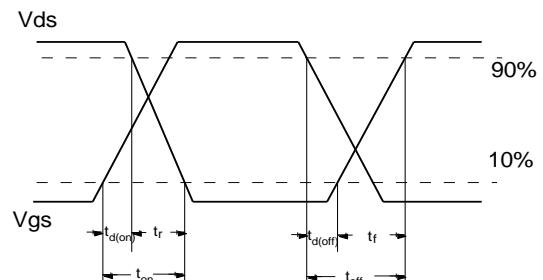
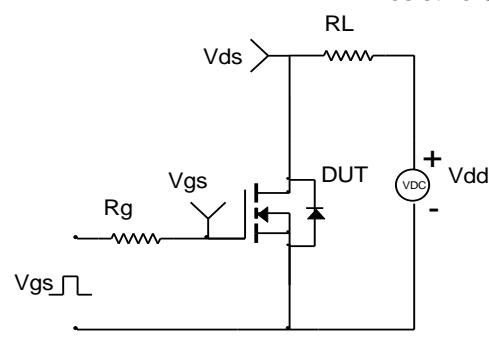
Figure 12: Maximum Forward Biased Safe Operating Area

## Test Circuit and Waveform

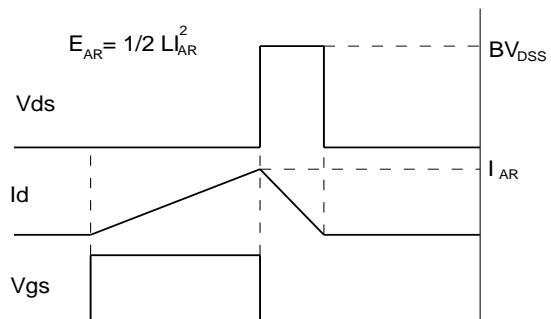
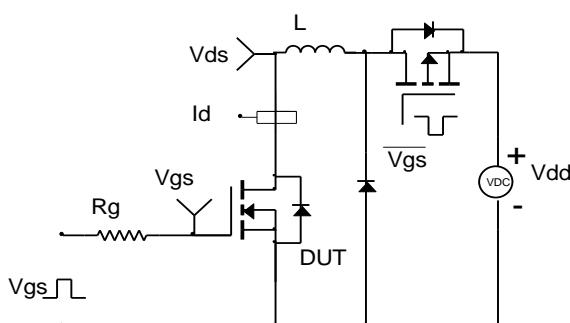
Gate Charge Test Circuit & Waveform



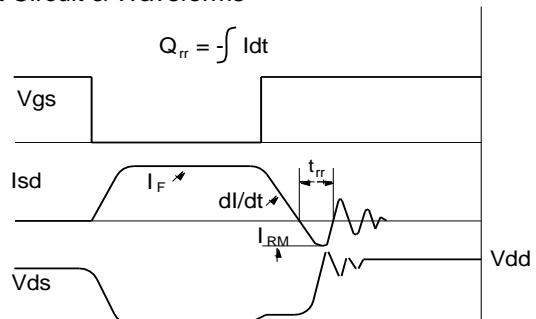
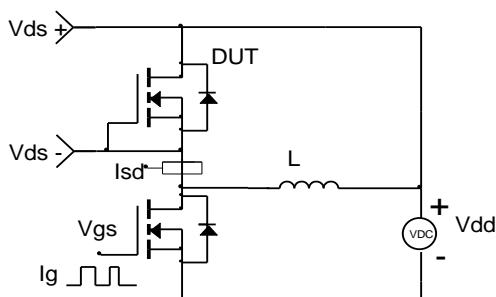
Resistive Switching Test Circuit & Waveforms



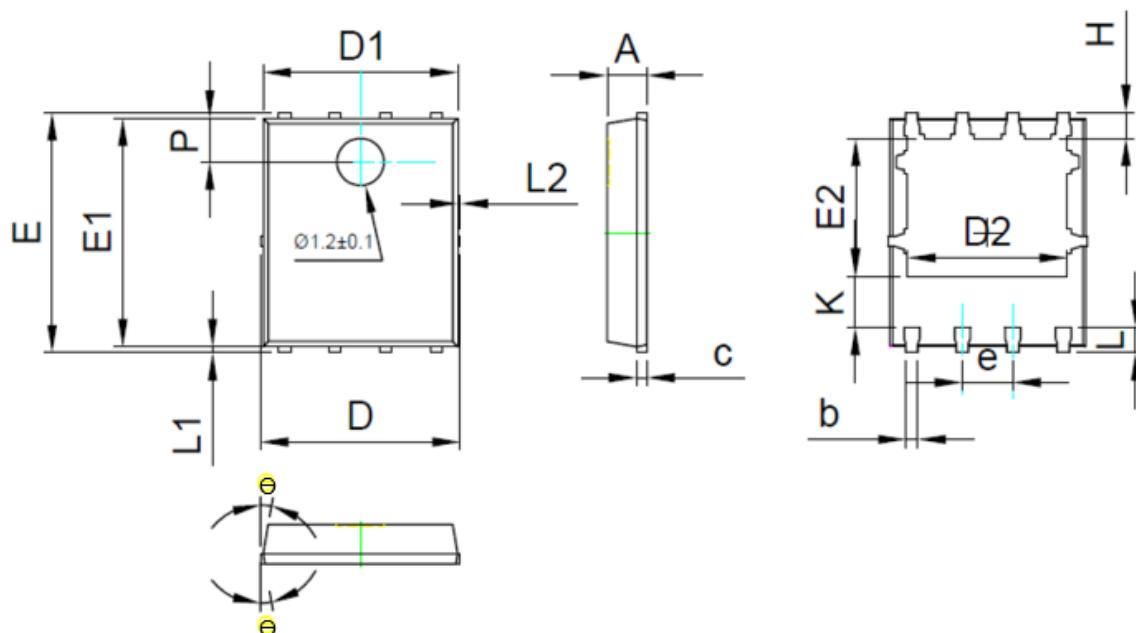
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



## Package Outlines



**COMMON DIMENSIONS**  
( UNITS OF MEASURE = MILLIMETER )

SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.35	0.40	0.45
c	0.21	0.25	0.34
D	-	-	5.1
D1	4.85	4.90	4.95
D2	3.96	4.01	4.06
e	1.27 BSC		
E	5.95	6.00	6.05
E1	5.70	5.75	5.80
E2	3.425	3.475	3.525
H	0.60	0.65	0.70
K	1.29	-	-
L	0.60	0.65	0.70
L1	0.05	0.15	0.25
L2	-	-	0.12
Θ	8°	10°	12°
P	1.05	1.10	1.15